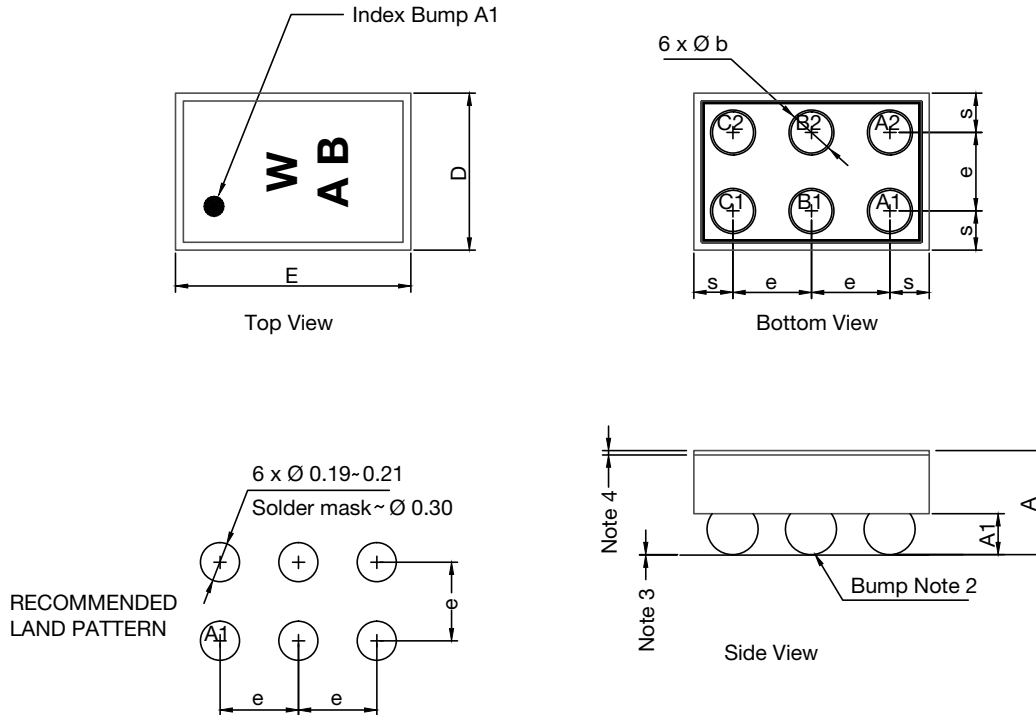


WCSP6: 6 Bumps

(2 x 3, 0.4 mm pitch, 208 μm bump height, 0.8 mm x 1.2 mm die size)



DIMENSION	MILLIMETERS ⁽⁵⁾			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.515	0.530	0.545	0.0203	0.0209	0.0215
A1	0.183	0.208	0.233	0.0072	0.0082	0.0092
b	0.234	0.260	0.312	0.0092	0.0102	0.0123
e	0.400			0.0157		
s	0.160	0.180	0.200	0.0063	0.0071	0.0078
D	0.720	0.760	0.800	0.0283	0.0299	0.0315
E	1.120	1.160	1.200	0.0441	0.0457	0.0472

Notes (unless otherwise specified)

- (1) Laser mark on the silicon die back coated with an epoxy film.
- (2) Bumps are SAC396.
- (3) 0.050 max. co-planarity.
- (4) Laminate tape thickness is 0.022 mm.
- (5) Use millimeters as the primary measurement.

ECN: S13-1793-Rev. A, 26-Aug-13
 DWG: 6018